

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

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TOTAL MASS (g) : 0.023788

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001591 | 1000000 | 66881.4375 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.009711 | 975000 | 408224.8125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000239 | 24000 | 10046.9287109 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000003 | 300 | 126.112091064 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000007 | 700 | 294.261535645 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.009960 | 1000000 | 418692.15625 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000455 | 1000000 | 19142.2460938 | | |
| | | External Plating Total: | | | | 0.000455 | 1000000 | 19142.2460938 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000225 | 1000000 | 9458.40625 | | |
| Internal Plating Total: | | | | 0.000225 | 1000000 | 9458.40625 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000778 | 750000 | 32705.0644531 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000259 | 250000 | 10887.6757812 | | |
| Die Attach Total: | | | | 0.001037 | 1000000 | 43592.7421875 | | |
| Encapsulation | FILLED EPOXY RESIN | Resin (EP) | | 0.001153 | 110000 | 48469.078125 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000105 | 10000 | 4413.92285156 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.008908 | 850000 | 374468.8125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000314 | 30000 | 13199.7314453 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000000 | 0 | 0 | | |
| | | Encapsulation Total: | | | | 0.010480 | 1000000 | 440551.5625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000040 | 1000000 | 1681.49438477 | | |
| | | | | | TOTAL MASS (g) : | 0.023788 | | |